

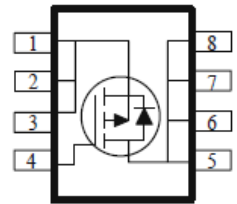
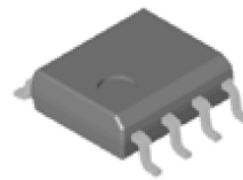
P-Channel 30-V (D-S) MOSFET

Key Features:

- Low $r_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed

Typical Applications:

- White LED boost converters
- Automotive Systems
- Industrial DC/DC Conversion Circuits



PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (m Ω)	I_D (A)
-30	5 @ $V_{GS} = -10V$	-21
	7 @ $V_{GS} = -4.5V$	-17

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Limit	Units
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^a	$T_A = 25^\circ C$	I_D	-21	A
	$T_A = 70^\circ C$		-17	
Pulsed Drain Current ^b		I_{DM}	-80	
Continuous Source Current (Diode Conduction) ^a		I_S	-4.8	A
Power Dissipation ^a	$T_A = 25^\circ C$	P_D	3.1	W
	$T_A = 70^\circ C$		2.2	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ C$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$t \leq 10$ sec	$R_{\theta JA}$	40	$^\circ C/W$
	Steady State		80	

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

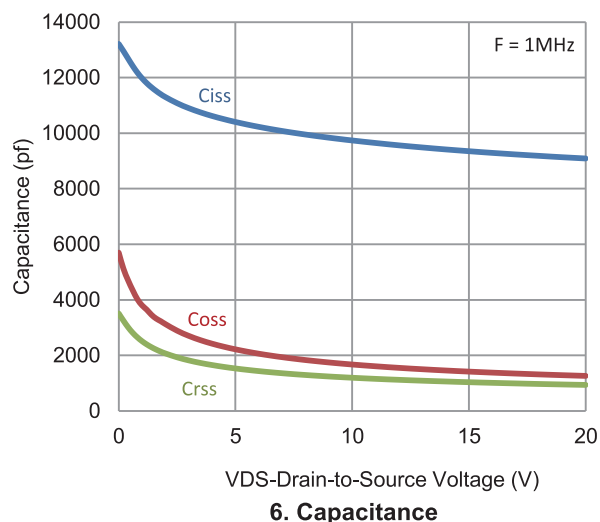
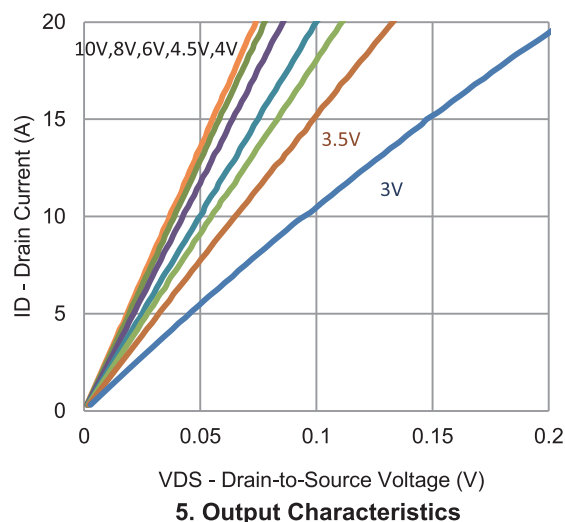
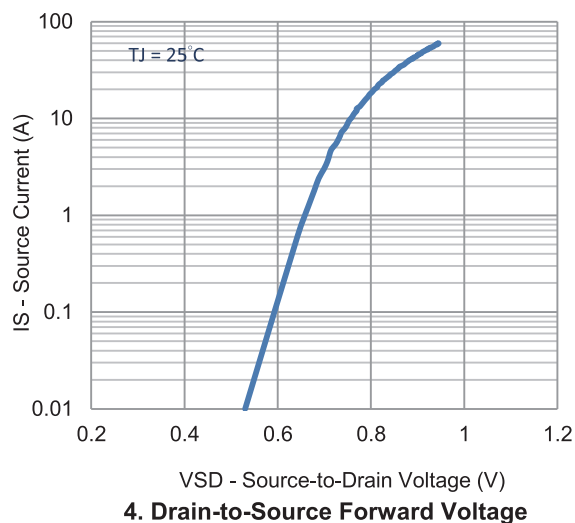
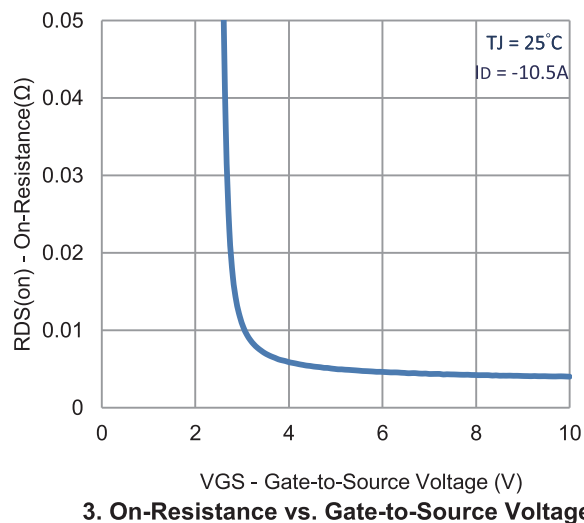
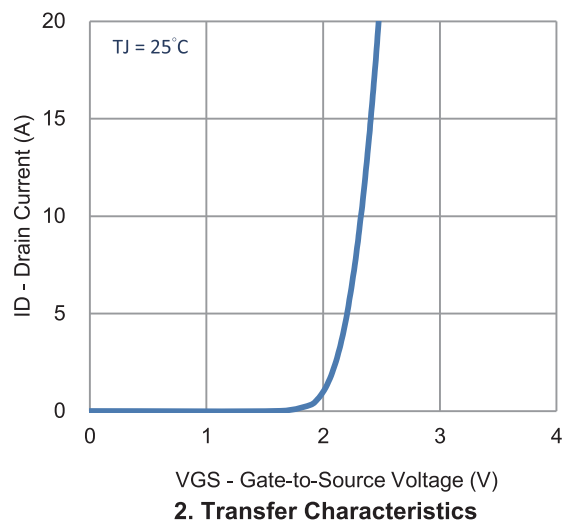
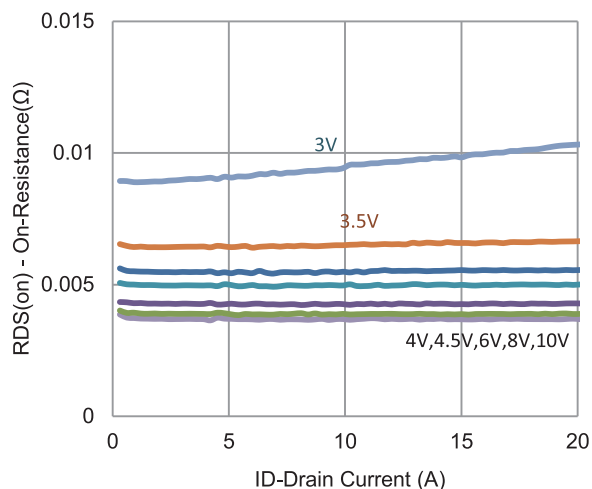
Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 \mu A$	1			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24 V, V_{GS} = 0 V$			-1	μA
		$V_{DS} = -24 V, V_{GS} = 0 V, T_J = 55^\circ C$			-25	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = -5 V, V_{GS} = -10 V$	-30			A
Drain-Source On-Resistance ^a	$r_{DS(on)}$	$V_{GS} = -10 V, I_D = -10.5 A$			5	m Ω
		$V_{GS} = -4.5 V, I_D = -8.5 A$			7	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -15 V, I_D = -10.5 A$		32		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -2.4 A, V_{GS} = 0 V$		-0.68		V
Dynamic ^b						
Total Gate Charge	Q_g	$V_{DS} = -15 V, V_{GS} = -4.5 V,$ $I_D = -10.5 A$		136		nC
Gate-Source Charge	Q_{gs}			31		
Gate-Drain Charge	Q_{gd}			59		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = -15 V, R_L = 1.9 \Omega,$ $I_D = -10.5 A,$ $V_{GEN} = -10 V, R_{GEN} = 6 \Omega$		19		ns
Rise Time	t_r			64		
Turn-Off Delay Time	$t_{d(off)}$			365		
Fall Time	t_f			224		
Input Capacitance	C_{iss}	$V_{DS} = -15 V, V_{GS} = 0 V, f = 1 MHz$		9350		pF
Output Capacitance	C_{oss}			1415		
Reverse Transfer Capacitance	C_{rss}			1034		

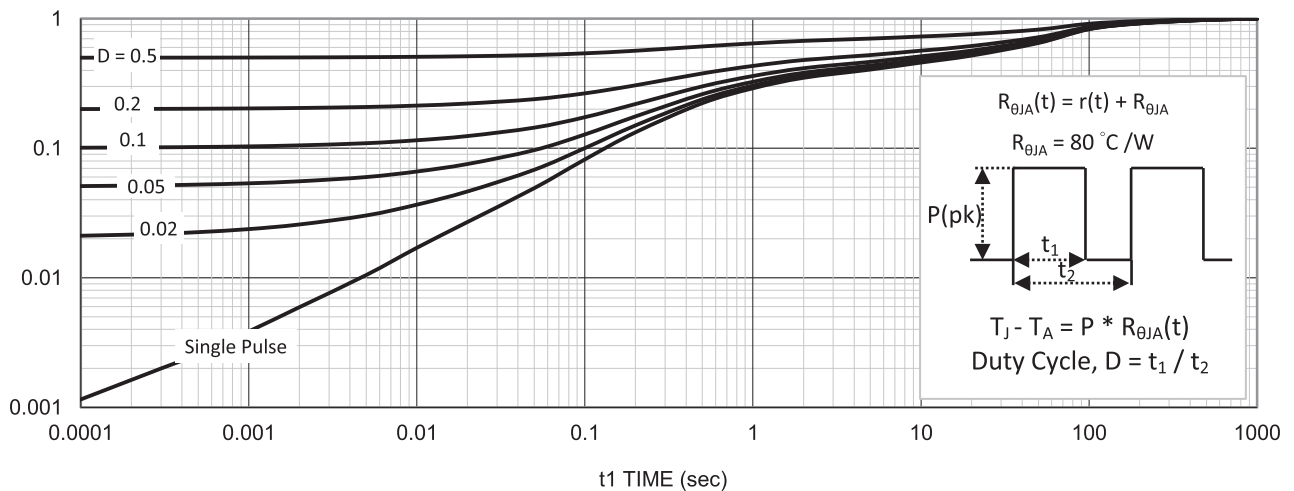
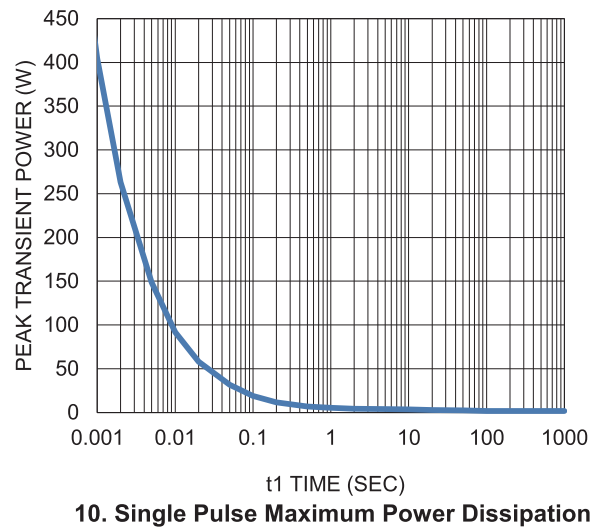
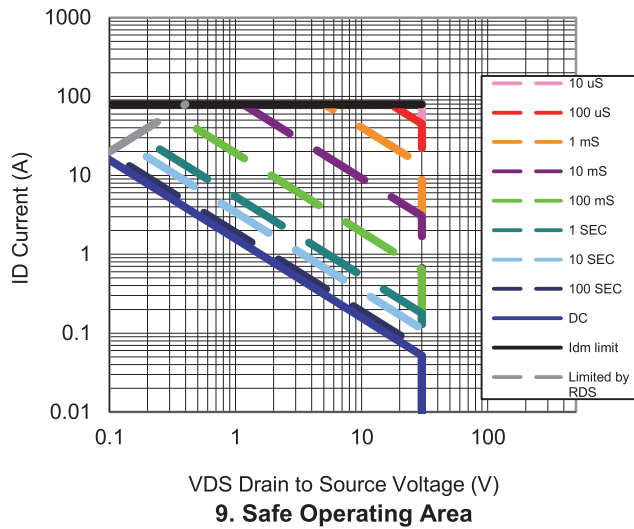
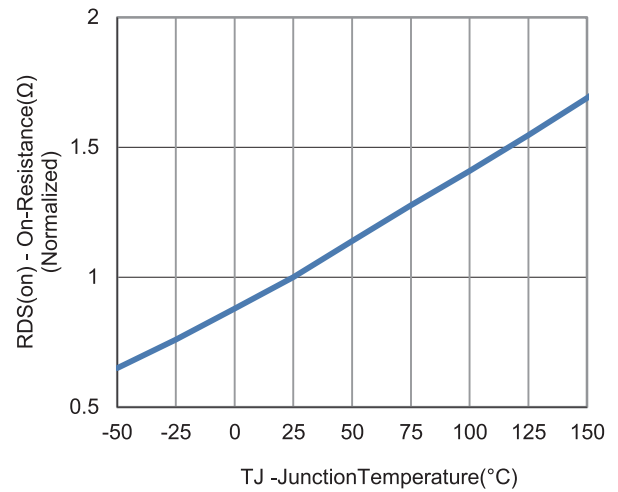
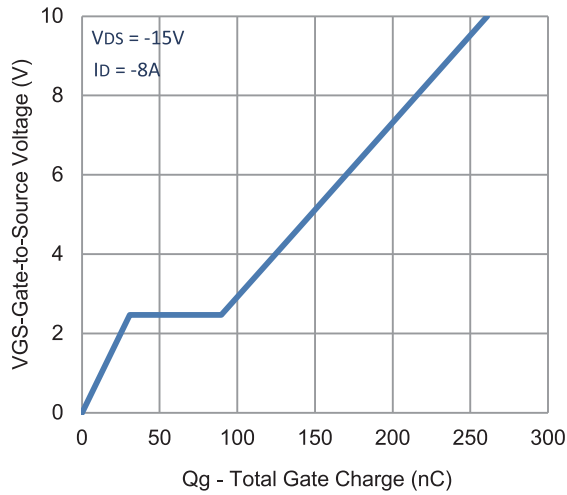
Notes

- a. Pulse test: PW $\leq$ 300 μ s duty cycle $\leq$ 2%.
- b. Guaranteed by design, not subject to production testing.

Typical Electrical Characteristics

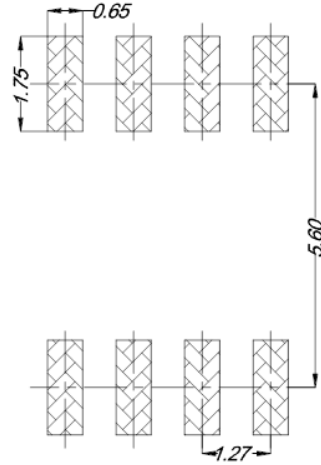
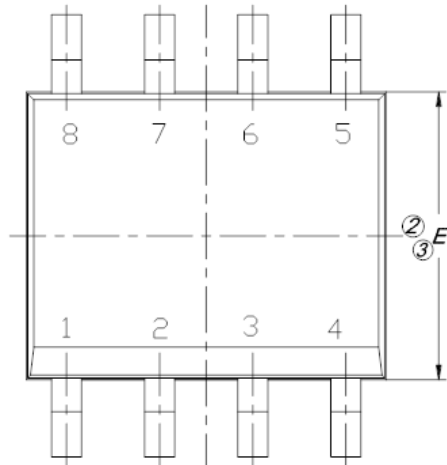


Typical Electrical Characteristics

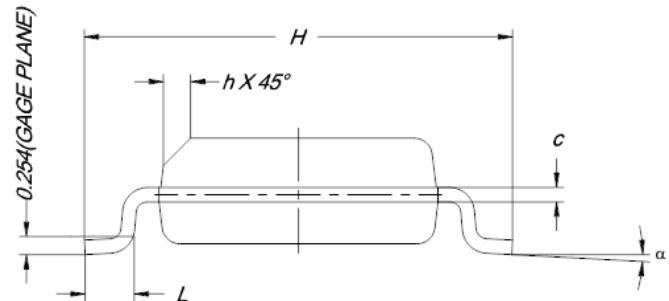
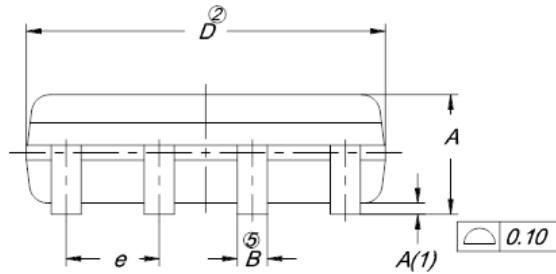


Package Information

Land Pattern (Only for Reference)



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.35	1.55	1.75
A(1)	0.10	0.18	0.25
B	0.38	0.45	0.51
C	0.19	0.22	0.25
D	4.80	4.90	5.00
E	3.80	3.90	4.00
e	1.27 BSC		
H	5.80	6.00	6.20
L	0.50	0.72	0.93
α	0°	4°	8°
h	0.25	0.38	0.50



Note:

1. All Dimension Are In mm.
2. Package Body Sizes Exclude Mold Flash, Protrusion Or Gate Burrs. Mold Flash, Protrusion Or Gate Burrs Shall Not Exceed 0.10 mm Per Side.
3. Package Body Sizes Determined At The Outermost Extremes Of The Plastic Body Exclusive Of Mold Flash, Tie Bar Burrs, Gate Burrs And Interlead Flash, But Including Any Mismatch Between The Top And Bottom Of The Plastic Body.
4. The Package Top May Be Smaller Than The Package Bottom.
5. Dimension "B" Does Not Include Dambar Protrusion. Allowable Dambar Protrusion Shall Be 0.08 mm Total In Excess Of "B" Dimension At Maximum Material Condition. The Dambar Cannot Be Located On The Lower Radius Of The Foot.